

# STP36NF03L

# N-CHANNEL 30V - 0.015 Ω - 40A TO-220 LOW GATE CHARGE STripFET™II POWER MOSFET

#### PRELIMINARY DATA

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STP36NF03L	30 V	<0.02Ω	36 A

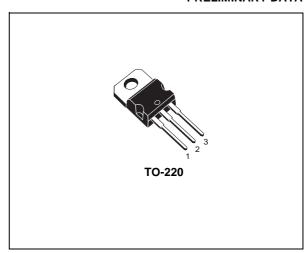
- TYPICAL  $R_{DS}(on) = 0.015 \Omega$
- TYPICAL Q<sub>g</sub> = 18 nC @ 10V
- OPTIMAL R<sub>DS(on)</sub> x Qg TRADE-OFF
- CONDUCTION LOSSES REDUCED
- SWITCHING LOSSES REDUCED

#### **DESCRIPTION**

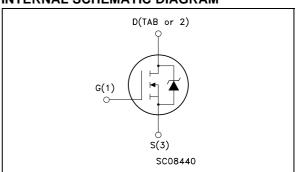
This application specific Power MOSFET is the third genaration of STMicroelectronis unique "Single Feature Size<sup>TM</sup>" strip-based process. The resulting transistor shows the best trade-off between on-resistance and gate charge. When used as high and low side in buck regulators, it gives the best performance in terms of both conduction and switching losses. This is extremely important for motherboards where fast switching and high efficiency are of paramount importance.

#### **APPLICATIONS**

 SPECIFICALLY DESIGNED AND OPTIMISED FOR HIGH EFFICIENCY CPU CORE DC/DC CONVERTERS



#### **INTERNAL SCHEMATIC DIAGRAM**



#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source Voltage (V <sub>GS</sub> = 0)	30	V
$V_{DGR}$	Drain-gate Voltage (R <sub>GS</sub> = 20 kΩ)	30	V
$V_{GS}$	Gate- source Voltage	± 18	V
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 25°C	36	A
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 100°C 25		A
I <sub>DM</sub> (•)	Drain Current (pulsed)	144	A
P <sub>tot</sub>	Total Dissipation at T <sub>C</sub> = 25°C	75	W
	Derating Factor	0.5	W/°C
T <sub>stg</sub>	Storage Temperature	-65 to 175	°C
Tj	Max. Operating Junction Temperature	175	°C

<sup>(•)</sup> Pulse width limited by safe operating area

February 2002 1/6

### THERMAL DATA

	Rthj-case Rthj-amb T <sub>l</sub>	Thermal Resistance Junction-case Thermal Resistance Junction-ambient Maximum Lead Temperature For Soldering Purpose	Max Max Typ	2 62.5 300	°C/W °C/W	
--	---	---	-------------------	------------------	--------------	--

# **ELECTRICAL CHARACTERISTICS** (T<sub>case</sub> = 25 °C unless otherwise specified)

### OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A$ $V_{GS} = 0$	30			٧
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	$V_{DS}$ = Max Rating $V_{DS}$ = Max Rating $T_{C}$ = 125°C			1 10	μA μA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 18V			±100	nA

# ON (\*)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$	I <sub>D</sub> = 250 μA	1			V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10 V V <sub>GS</sub> = 5 V	I <sub>D</sub> = 18 A I <sub>D</sub> = 9 A		0.015 0.026	0.020 0.035	Ω Ω

### **DYNAMIC**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g <sub>fs</sub> (*)	Forward Transconductance	V <sub>DS</sub> >I <sub>D(on)</sub> xR <sub>DS(on)max</sub> I <sub>D</sub> =18 A		20		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25V$ , $f = 1 MHz$ , $V_{GS} = 0$		750 270 60		pF pF pF

# **ELECTRICAL CHARACTERISTICS** (continued)

### SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub>	Turn-on Delay Time Rise Time	$\begin{array}{ccc} V_{DD} = 15 \text{ V} & I_D = 18 \text{ A} \\ R_G = 4.7 \ \Omega & V_{GS} = 4.5 \text{ V} \\ \text{(Resistive Load, Figure 3)} \end{array}$		16 200		ns ns
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Total Gate Charge Gate-Source Charge Gate-Drain Charge	V <sub>DD</sub> =24 V I <sub>D</sub> =32 A V <sub>GS</sub> =10V		18 3 5	21	nC nC nC

#### **SWITCHING OFF**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(off)</sub>	Turn-off Delay Time Fall Time	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$		35 40		ns ns

### SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub> I <sub>SDM</sub> (•)	Source-drain Current Source-drain Current (pulsed)				36 144	A A
V <sub>SD</sub> (*)	Forward On Voltage	I <sub>SD</sub> = 36 A V <sub>GS</sub> = 0			1.5	V
t <sub>rr</sub> Q <sub>rr</sub> I <sub>RRM</sub>	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$\begin{split} I_{SD} = 36 \text{ A} & \text{di/dt} = 100 \text{A/}\mu\text{s} \\ V_{DD} = 15 \text{ V} & T_j = 150 ^{\circ}\text{C} \\ \text{(see test circuit, Figure 5)} \end{split}$		50 80 2		ns nC A

<sup>(\*)</sup>Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %.
(•)Pulse width limited by safe operating area.

Fig. 1: Unclamped Inductive Load Test Circuit

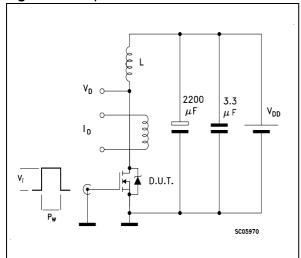
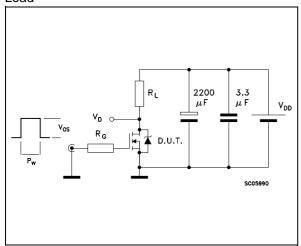


Fig. 3: Switching Times Test Circuits For Resistive Load



**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times

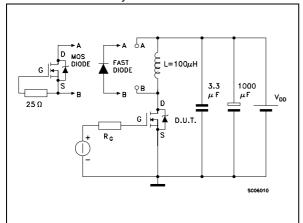


Fig. 2: Unclamped Inductive Waveform

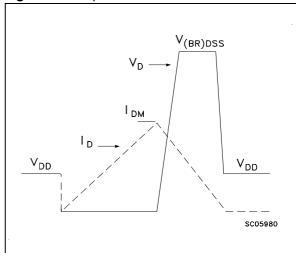
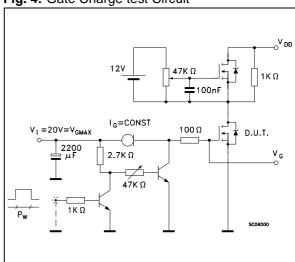
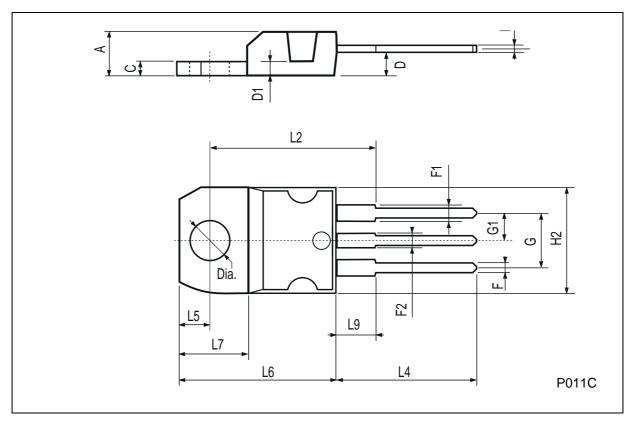


Fig. 4: Gate Charge test Circuit



# **TO-220 MECHANICAL DATA**

DIM.	mm					
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α	4.40		4.60	0.173		0.181
С	1.23		1.32	0.048		0.051
D	2.40		2.72	0.094		0.107
D1		1.27			0.050	
Е	0.49		0.70	0.019		0.027
F	0.61		0.88	0.024		0.034
F1	1.14		1.70	0.044		0.067
F2	1.14		1.70	0.044		0.067
G	4.95		5.15	0.194		0.203
G1	2.4		2.7	0.094		0.106
H2	10.0		10.40	0.393		0.409
L2		16.4			0.645	
L4	13.0		14.0	0.511		0.551
L5	2.65		2.95	0.104		0.116
L6	15.25		15.75	0.600		0.620
L7	6.2		6.6	0.244		0.260
L9	3.5		3.93	0.137		0.154
DIA.	3.75		3.85	0.147		0.151



Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is registered trademark of STMicroelectronics ® 2002 STMicroelectronics - All Rights Reserved

All other names are the property of their respective owners.

STMicroelectronics GROUP OF COMPANIES

Australia - Brazil - Canada - China - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States.

http://www.st.com